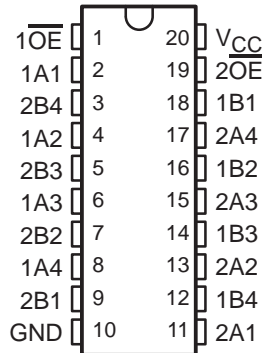


# SN74CBT3244 OCTAL FET BUS SWITCH

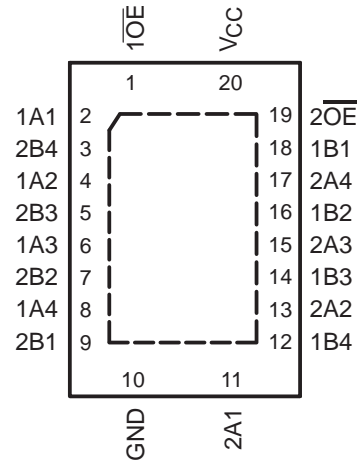
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- Standard '244-Type Pinout
- 5-Ω Switch Connection Between Two Ports
- TTL-Compatible Input Levels

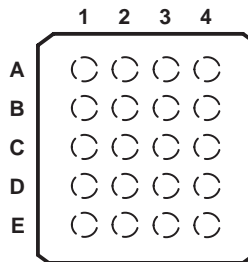
DB, DBQ, DGV, DW, OR PW PACKAGE  
(TOP VIEW)



RGY PACKAGE  
(TOP VIEW)



GQN OR ZQN PACKAGE  
(TOP VIEW)



## terminal assignments

	1	2	3	4
A	1A1	1OE	V <sub>CC</sub>	2OE
B	1A2	2A4	2B4	1B1
C	1A3	2B3	2A3	1B2
D	1A4	2A2	2B2	1B3
E	GND	2B1	2A1	1B4

## description/ordering information

### ORDERING INFORMATION

T <sub>A</sub>	PACKAGE†		ORDERABLE PART NUMBER	TOP-SIDE MARKING
-40°C to 85°C	QFN – RGY	Tape and reel	SN74CBT3244RGYR	CU244
	SOIC – DW	Tube	SN74CBT3244DW	CBT3244
		Tape and reel	SN74CBT3244DWR	
	SSOP – DB	Tape and reel	SN74CBT3244DBR	CU244
	SSOP (QSOP) – DBQ	Tape and reel	SN74CBT3244DBQR	CBT3244
	TSSOP – PW	Tube	SN74CBT3244PW	CU244
		Tape and reel	SN74CBT3244PWR	
	TVSOP – DGV	Tape and reel	SN74CBT3244DGV	CU244
VFBGA – GQN	Tape and reel	SN74CBT3244GQNR	CU244	
VFBGA – ZQN (Pb-free)		SN74CBT3244ZQNR		

† Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at [www.ti.com/sc/package](http://www.ti.com/sc/package).



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**TEXAS  
INSTRUMENTS**

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# SN74CBT3244 OCTAL FET BUS SWITCH

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## description/ordering information (continued)

The SN74CBT3244 provides eight bits of high-speed TTL-compatible bus switching. The SOIC, SSOP, TSSOP, and TVSOP packages provide a standard '244 device pinout. The low on-state resistance of the switch allows connections to be made with minimal propagation delay.

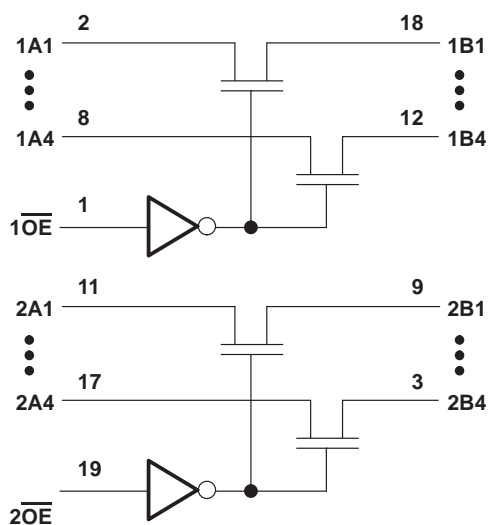
The device is organized as two 4-bit low-impedance switches with separate output-enable ( $\overline{OE}$ ) inputs. When  $\overline{OE}$  is low, the switch is on, and data can flow from port A to port B, or vice versa. When  $\overline{OE}$  is high, the switch is open, and the high-impedance state exists between the two ports.

To ensure the high-impedance state during power up or power down,  $\overline{OE}$  should be tied to  $V_{CC}$  through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

**FUNCTION TABLE**  
(each 4-bit bus switch)

INPUT $\overline{OE}$	FUNCTION
L	A port = B port
H	Disconnect

## logic diagram (positive logic)



Pin numbers shown are for the DB, DBQ, DGV, DW, RGY, and PW packages.

**absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†**

Supply voltage range, $V_{CC}$ .....	–0.5 V to 7 V
Input voltage range, $V_I$ (see Note 1) .....	–0.5 V to 7 V
Continuous channel current .....	128 mA
Clamp current, $I_K$ ( $V_{I/O} < 0$ ) .....	–50 mA
Package thermal impedance, $\theta_{JA}$ (see Note 2): DB package .....	70°C/W
(see Note 2): DBQ package .....	68°C/W
(see Note 2): DGV package .....	92°C/W
(see Note 2): DW package .....	58°C/W
(see Note 2): GQN/ZQN package .....	78°C/W
(see Note 2): PW package .....	83°C/W
(see Note 3): RGY package .....	37°C/W
Storage temperature range, $T_{stg}$ .....	–65°C to 150°C

† Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.  
 2. The package thermal impedance is calculated in accordance with JESD 51-7.  
 3. The package thermal impedance is calculated in accordance with JESD 51-5.

**recommended operating conditions (see Note 4)**

	MIN	MAX	UNIT
$V_{CC}$ Supply voltage	4.5	5.5	V
$V_{IH}$ High-level control input voltage	2		V
$V_{IL}$ Low-level control input voltage		0.8	V
$T_A$ Operating free-air temperature	–40	85	°C

NOTE 4: All unused control inputs of the device must be held at  $V_{CC}$  or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

**electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)**

PARAMETER	TEST CONDITIONS	MIN	TYP‡	MAX	UNIT	
$V_{IK}$	$V_{CC} = 4.5$ V, $I_I = -18$ mA			–1.2	V	
$I_I$	$V_{CC} = 5.5$ V, $V_I = 5.5$ V or GND			±5	µA	
$I_{CC}$	$V_{CC} = 5.5$ V, $I_O = 0$ , $V_I = V_{CC}$ or GND			50	µA	
$\Delta I_{CC}$ §	Control inputs $V_{CC} = 5.5$ V, One input at 3.4 V, Other inputs at $V_{CC}$ or GND			3.5	mA	
$C_i$	Control inputs $V_I = 3$ V or 0			3	pF	
$C_{iO(OFF)}$	$V_O = 3$ V or 0, $\overline{OE} = V_{CC}$			6	pF	
$r_{on}$ ¶	$V_{CC} = 4.5$ V	$V_I = 0$	$I_I = 64$ mA	5	7	Ω
			$I_I = 30$ mA	5	7	
		$V_I = 2.4$ V, $I_I = 15$ mA	10	15		

‡ All typical values are at  $V_{CC} = 5$  V,  $T_A = 25^\circ\text{C}$ .

§ This is the increase in supply current for each input that is at the specified TTL voltage level, rather than  $V_{CC}$  or GND.

¶ Measured by the voltage drop between the A and the B terminals at the indicated current through the switch. On-state resistance is determined by the lowest voltage of the two (A or B) terminals.

# SN74CBT3244 OCTAL FET BUS SWITCH

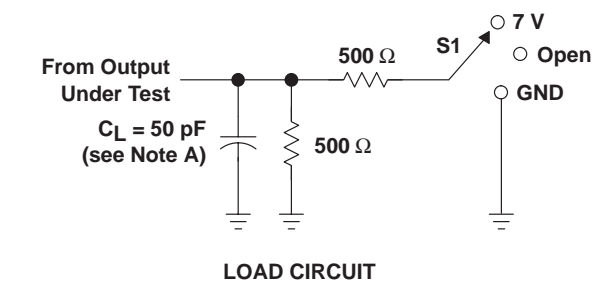
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switching characteristics over recommended operating free-air temperature range,  $C_L = 50 \text{ pF}$  (unless otherwise noted) (see Figure 1)

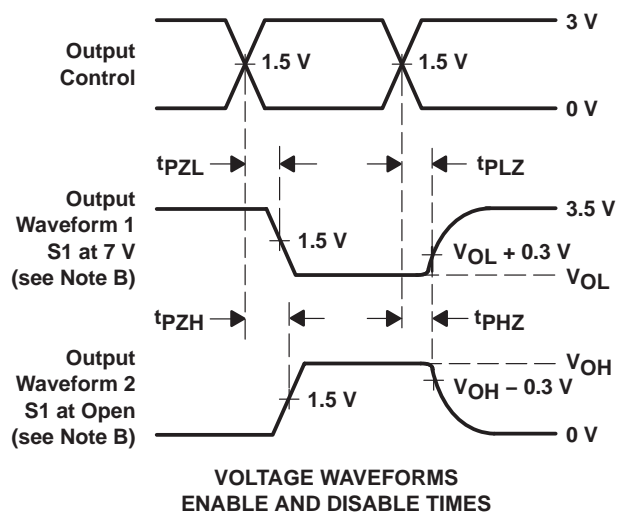
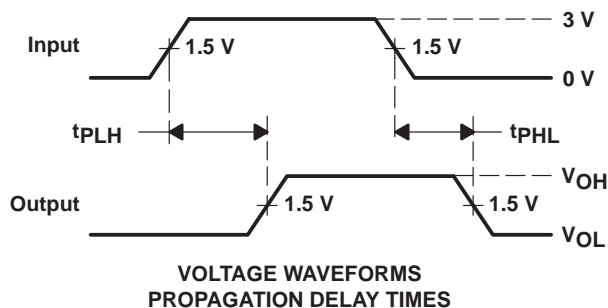
PARAMETER	FROM (INPUT)	TO (OUTPUT)	MIN	MAX	UNIT
$t_{pd}^\dagger$	A or B	B or A		0.25	ns
$t_{en}$	$\overline{OE}$	A or B	1	8.9	ns
$t_{dis}$	$\overline{OE}$	A or B	1	7.4	ns

$^\dagger$  This propagation delay is the calculated RC time constant of the typical on-state resistance of the switch and the specified load capacitance, when driven by an ideal voltage source (zero output impedance).

## PARAMETER MEASUREMENT INFORMATION



TEST	S1
$t_{pd}$	Open
$t_{PLZ}/t_{PZL}$	7 V
$t_{PHZ}/t_{PZH}$	Open



- NOTES:
- A.  $C_L$  includes probe and jig capacitance.
  - B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
  - C. All input pulses are supplied by generators having the following characteristics:  $PRR \leq 10 \text{ MHz}$ ,  $Z_O = 50 \Omega$ ,  $t_r \leq 2.5 \text{ ns}$ ,  $t_f \leq 2.5 \text{ ns}$ .
  - D. The outputs are measured one at a time with one transition per measurement.
  - E.  $t_{PLZ}$  and  $t_{PHZ}$  are the same as  $t_{dis}$ .
  - F.  $t_{PZL}$  and  $t_{PZH}$  are the same as  $t_{en}$ .
  - G.  $t_{PLH}$  and  $t_{PHL}$  are the same as  $t_{pd}$ .
  - H. All parameters and waveforms are not applicable to all devices.

Figure 1. Load Circuit and Voltage Waveforms

PACKAGING INFORMATION

Orderable Device	Status <sup>(1)</sup>	Package Type	Package Drawing	Pins	Package Qty	Eco Plan <sup>(2)</sup>	Lead/Ball Finish	MSL Peak Temp <sup>(3)</sup>
SN74CBT3244DBLE	OBSOLETE	SSOP	DB	20		None	Call TI	Call TI
SN74CBT3244DBQR	ACTIVE	SSOP/ QSOP	DBQ	20	2500	Pb-Free (RoHS)	CU NIPDAU	Level-2-260C-1 YEAR/ Level-1-235C-UNLIM
SN74CBT3244DBR	ACTIVE	SSOP	DB	20	2000	Pb-Free (RoHS)	CU NIPDAU	Level-2-260C-1 YEAR/ Level-1-235C-UNLIM
SN74CBT3244DGVR	ACTIVE	TVSOP	DGV	20	2000	Pb-Free (RoHS)	CU NIPDAU	Level-1-250C-UNLIM
SN74CBT3244DW	ACTIVE	SOIC	DW	20	25	Pb-Free (RoHS)	CU NIPDAU	Level-2-250C-1 YEAR/ Level-1-235C-UNLIM
SN74CBT3244DWR	ACTIVE	SOIC	DW	20	2000	Pb-Free (RoHS)	CU NIPDAU	Level-2-250C-1 YEAR/ Level-1-235C-UNLIM
SN74CBT3244GQNR	ACTIVE	VFBGA	GQN	20	1000	None	SNPB	Level-1-240C-UNLIM
SN74CBT3244PW	ACTIVE	TSSOP	PW	20	70	Pb-Free (RoHS)	CU NIPDAU	Level-1-250C-UNLIM
SN74CBT3244PWLE	OBSOLETE	TSSOP	PW	20		None	Call TI	Call TI
SN74CBT3244PWR	ACTIVE	TSSOP	PW	20	2000	Pb-Free (RoHS)	CU NIPDAU	Level-1-250C-UNLIM
SN74CBT3244RGYR	ACTIVE	QFN	RGY	20	1000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1YEAR
SN74CBT3244ZQNR	ACTIVE	VFBGA	ZQN	20	1000	Pb-Free (RoHS)	SNAGCU	Level-1-260C-UNLIM

<sup>(1)</sup> The marketing status values are defined as follows:

**ACTIVE:** Product device recommended for new designs.

**LIFEBUY:** TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

**NRND:** Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

**PREVIEW:** Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

<sup>(2)</sup> Eco Plan - May not be currently available - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

**None:** Not yet available Lead (Pb-Free).

**Pb-Free (RoHS):** TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

**Green (RoHS & no Sb/Br):** TI defines "Green" to mean "Pb-Free" and in addition, uses package materials that do not contain halogens, including bromine (Br) or antimony (Sb) above 0.1% of total product weight.

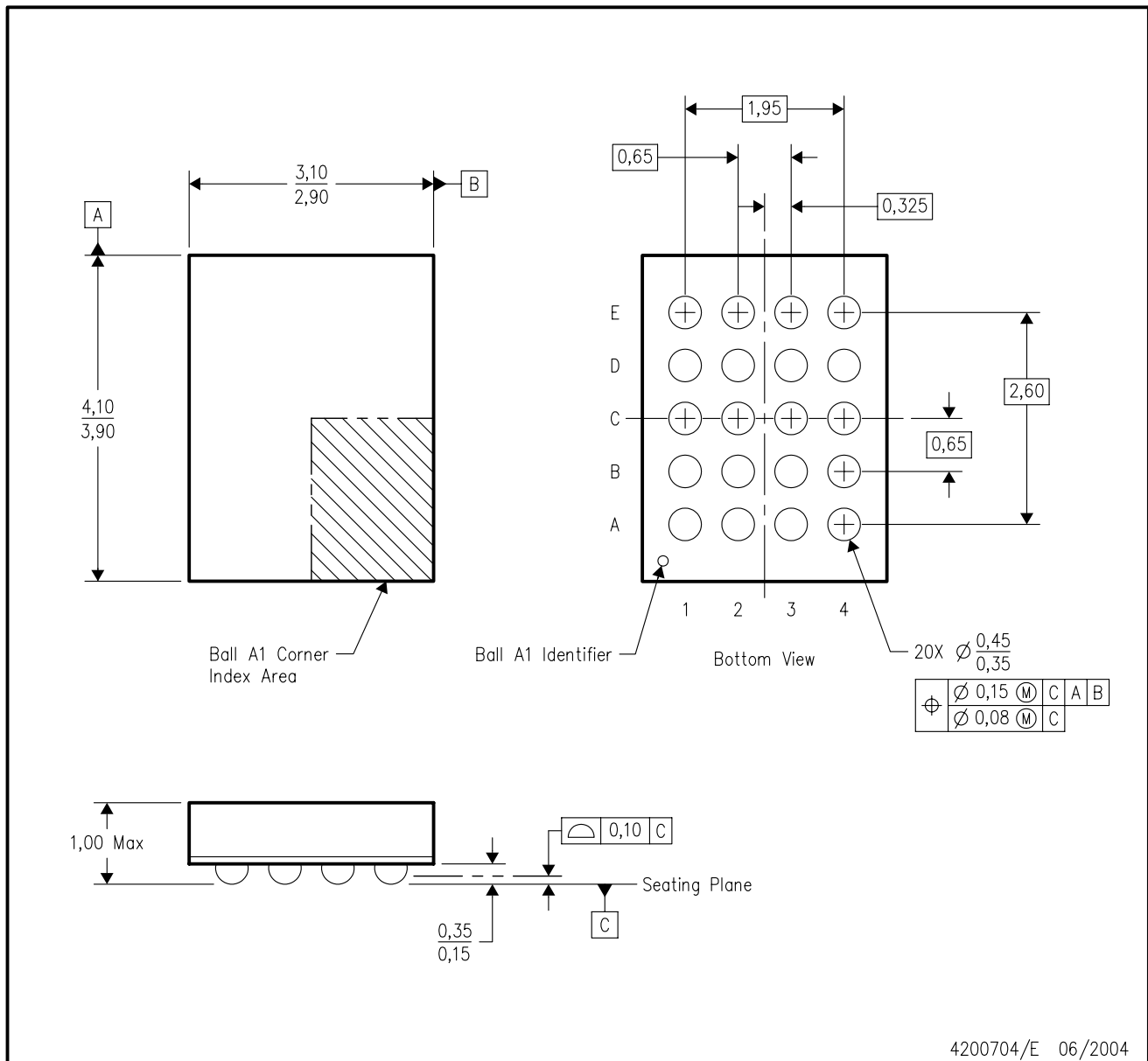
<sup>(3)</sup> MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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GQN (R-PBGA-N20)

PLASTIC BALL GRID ARRAY

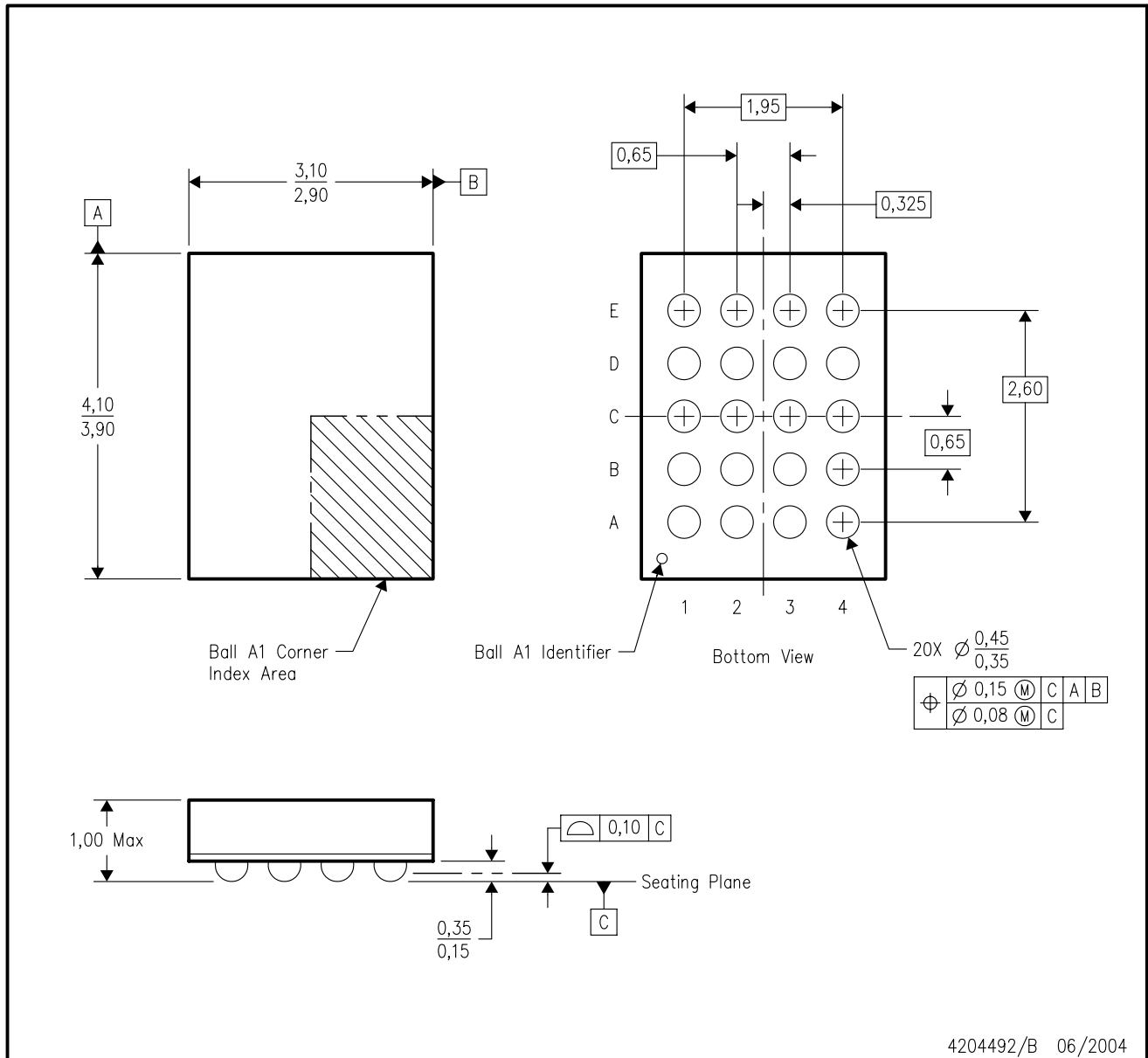


4200704/E 06/2004

- NOTES:
- A. All linear dimensions are in millimeters.
  - B. This drawing is subject to change without notice.
  - C. Falls within JEDEC MO-225 variation BC.
  - D. This package is tin-lead (SnPb). Refer to the 20 ZQN package (drawing 4204492) for lead-free.

ZQN (R-PBGA-N20)

PLASTIC BALL GRID ARRAY



- NOTES:
- A. All linear dimensions are in millimeters.
  - B. This drawing is subject to change without notice.
  - C. Falls within JEDEC MO-225 variation BC.
  - D. This package is lead-free. Refer to the 20 GQN package (drawing 4200704) for tin-lead (SnPb).

DGV (R-PDSO-G\*\*)

PLASTIC SMALL-OUTLINE

24 PINS SHOWN



4073251/E 08/00

- NOTES: A. All linear dimensions are in millimeters.  
 B. This drawing is subject to change without notice.  
 C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15 per side.  
 D. Falls within JEDEC: 24/48 Pins – MO-153  
 14/16/20/56 Pins – MO-194

DW (R-PDSO-G20)

PLASTIC SMALL-OUTLINE PACKAGE

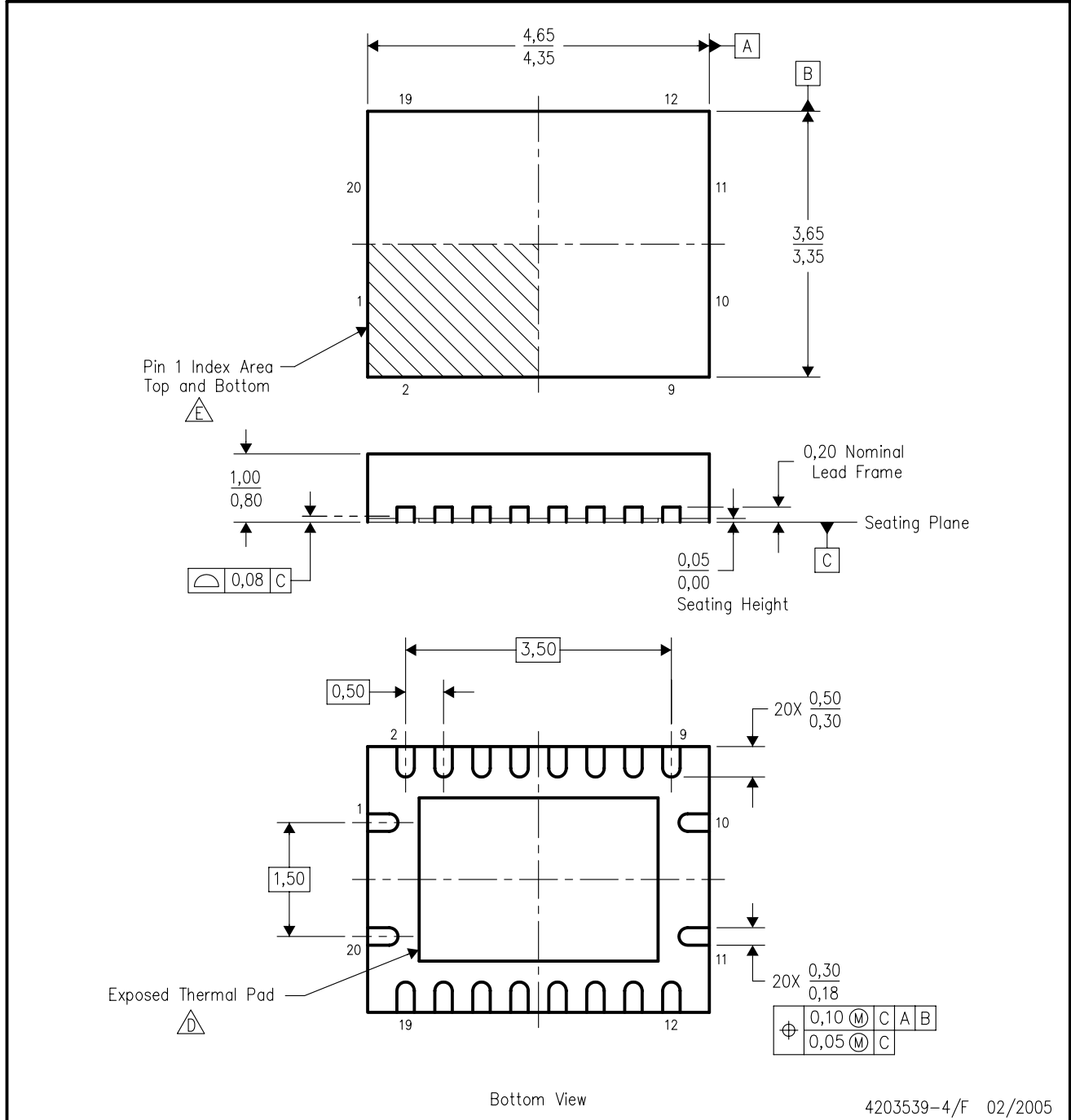


- NOTES:
- A. All linear dimensions are in inches (millimeters).
  - B. This drawing is subject to change without notice.
  - C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
  - D. Falls within JEDEC MS-013 variation AC.



RGY (R-PQFP-N20)

PLASTIC QUAD FLATPACK



4203539-4/F 02/2005

- NOTES:
- A. All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M-1994.
  - B. This drawing is subject to change without notice.
  - C. QFN (Quad Flatpack No-Lead) package configuration.
  - The package thermal pad must be soldered to the board for thermal and mechanical performance. See the Product Data Sheet for details regarding the exposed thermal pad dimensions.
  - Pin 1 identifiers are located on both top and bottom of the package and within the zone indicated. The Pin 1 identifiers are either a molded, marked, or metal feature.
  - F. Package complies to JEDEC MO-241 variation BC.

DB (R-PDSO-G\*\*)

PLASTIC SMALL-OUTLINE

28 PINS SHOWN



- NOTES: A. All linear dimensions are in millimeters.  
 B. This drawing is subject to change without notice.  
 C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.  
 D. Falls within JEDEC MO-150

PW (R-PDSO-G\*\*)

PLASTIC SMALL-OUTLINE PACKAGE

14 PINS SHOWN



4040064/F 01/97

- NOTES: A. All linear dimensions are in millimeters.  
 B. This drawing is subject to change without notice.  
 C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.  
 D. Falls within JEDEC MO-153

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